

Abstract of the Disclosure:

An electronic component with shielding is described. The component has a semiconductor chip with a semiconductor substrate. Disposed in a region of a rear side of the 5 semiconductor substrate is an electrically conductive buried layer. The buried layer is connected via a ground lead, disposed within the semiconductor substrate, to a contact area and an external ground potential. Furthermore, the invention relates to a method for producing an electronic component of 10 this type.

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